Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	257/666-676 and @pd>"20050801"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:28
L2	354	257/666-676,678,687.ccls. and @pd>"20050801"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:28
L3	25	leadframe and rough$4 and @pd>"20050801"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:33
L4	3	((leadframe (lead adj frame)) same rough$4) and etch$3 and (acid sulfuric peroxide ('"H.sub.2'" adj '"SO.sub.2'") ('"H.sub.2'" adj '"O.sub.2'")) and @pd>"20050801"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:33
L5	0	((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening rougher) and @pd>"20050801"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:34
L6	0	((leadframe (lead adj frame)) and organo-metallic).clm.	US-PGPUB	OR	ON	2005/12/10 18:35
S1	358	leadframe and rough$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:33
S2	2221	(leadframe (lead adj frame)) and rough$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/05 20:09
S3	1002	(leadframe (lead adj frame)) and rough$4 and etch$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/05 20:10
S4	376	(leadframe (lead adj frame)) and rough$4 and etch$3 and (acid sulfuric peroxide ('"H.sub.2'" adj '"SO.sub.2'") ('"H.sub.2'" adj '"O.sub.2'"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/05 20:17

S5	72	((leadframe (lead adj frame)) same rough$4) and etch$3 and (acid sulfuric peroxide ('"H.sub.2'" adj '"SO.sub.2'") ('"H.sub.2'" adj '"O.sub.2'"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:33
S6	5	257/666-676	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:27
S7	8313	257/666-676.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 11:55
S8	130	257/666-676.ccls. and ((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 12:57
S9	3	257/666-676.ccls. and ((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 12:57
S10	3	257/666-676.ccls. and ((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening rougher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 13:17
S11	0	257/678.ccls. and ((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening rougher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 13:17
S12	0	257/687.ccls. and ((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening rougher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 13:18
S13	0	438/622.ccls. and ((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening rougher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 13:18
S14	6	((etch$3 with (wet chemical$3)) with (leadframe (lead adj frame) lead-frame)) same (roughen rough roughening rougher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/10 18:34